Memory FRAM

128K (16 K × 8) Bit SPI

MB85RS128A

■ DESCRIPTION

MB85RS128A is a FRAM (Ferroelectric Random Access Memory) chip in a configuration of 16,384 words \times 8 bits, using the ferroelectric process and silicon gate CMOS process technologies for forming the nonvolatile memory cells.

MB85RS128A adopts the Serial Peripheral Interface (SPI).

The MB85RS128A is able to retain data without using a back-up battery, as is needed for SRAM. The memory cells used in the MB85RS128A can be used for 10¹⁰ read/write operations, which is a significant improvement over the number of read and write operations supported by Flash memory and E²PROM. MB85RS128A does not take long time to write data unlike Flash memories nor E²PROM, and MB85RS128A takes no wait time.

■ FEATURES

• Bit configuration : 16,384 words \times 8 bits

• Serial Peripheral Interface : SPI (Serial Peripheral Interface)

Correspondent to SPI mode 0 (0, 0) and mode 3 (1, 1)

Operating frequency
 Read/write endurance
 Data retention
 Operating power supply voltage
 25 MHz (Max)
 10¹⁰ times/bit
 10 years (+55 °C)
 3.0 V to 3.6 V

Low power consumption : Operating power supply current 5 mA (Typ @25 MHz)

Standby current 9 µA (Typ)

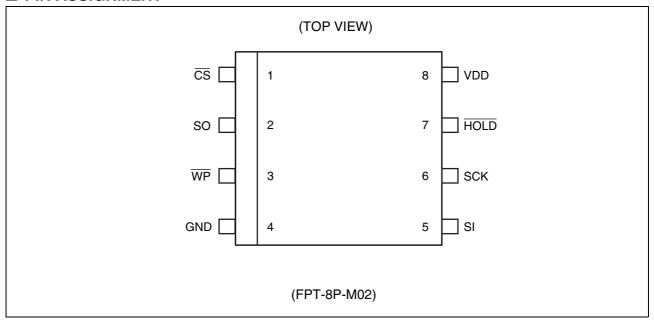
• Operating temperature range : − 40 °C to + 85 °C

Package : 8-pin plastic SOP (FPT-8P-M02)

RoHS compliant



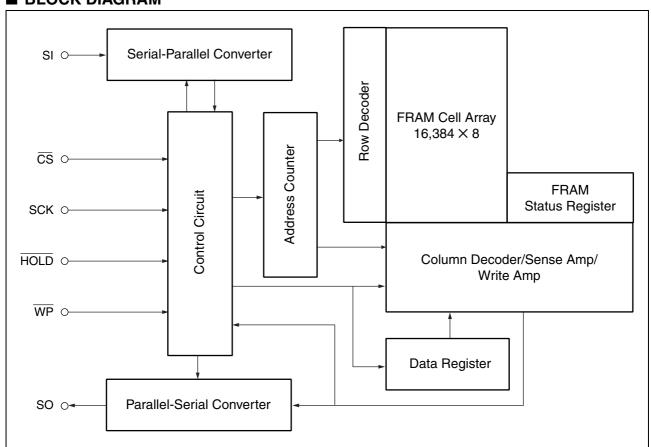
■ PIN ASSIGNMENT



■ PIN FUNCTIONAL DESCRIPTIONS

Pin No.	Pin Name	Functional description
1	CS	Chip Select pin This is an input pin to make chips select. When \overline{CS} is the "H" level, device is in deselect (standby) status as long as device is not write status internally, and SO becomes High-Z. Inputs from other pins are ignored at this time. When \overline{CS} is the "L" level, device is in select (active) status. \overline{CS} has to be the "L" level before inputting op-code.
3	WP	Write Protect pin This is a pin to control writing to a status register. When \overline{WP} is the "L" level, writing to a status register is not operated.
7	HOLD	Hold pin This pin is used to interrupt serial input/output without making chips deselect. When HOLD is the "L" level, hold operation is activated, SO becomes High-Z, SCK and SI become don't care. While the hold operation, \overline{CS} has to be retained the "L" level.
6	SCK	Serial Clock pin This is a clock input pin to input/output serial data. SI is loaded synchronously to a rising edge, SO is output synchronously to a falling edge.
5	SI	Serial Data Input pin This is an input pin of serial data. This inputs op-code, address, and writing data.
2	SO	Serial Data Output pin This is an output pin of serial data. Reading data of FRAM memory cell array and status register data are output. This is High-Z during standby.
8	VDD	Supply Voltage pin
4	GND	Ground pin

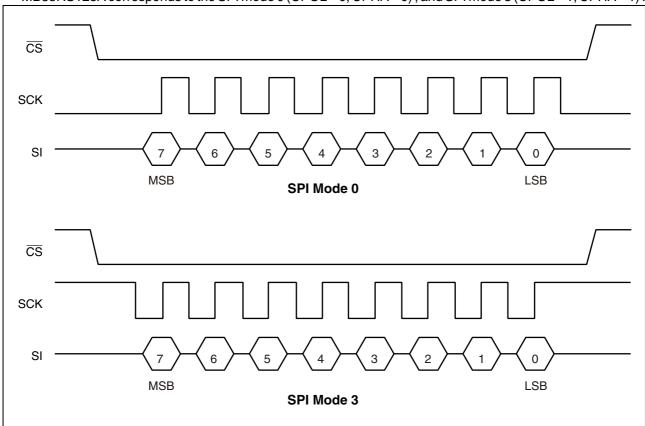
■ BLOCK DIAGRAM



■ SPI MODE

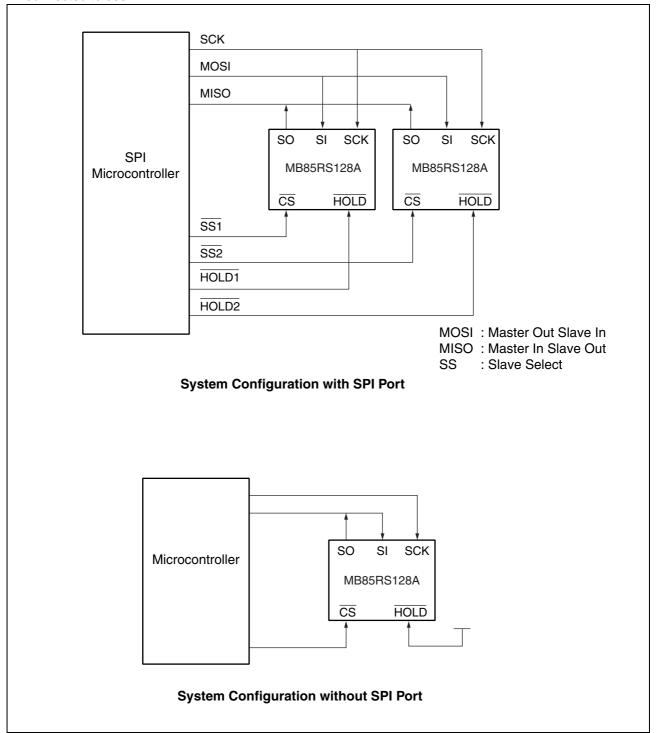
4

 $MB85RS128A\,corresponds\,to\,the\,SPI\,mode\,0\,(CPOL=0,CPHA=0)\,, and\,SPI\,mode\,3\,(CPOL=1,CPHA=1)\,.$



■ SERIAL PERIPHERAL INTERFACE (SPI)

MB85RS128A works as a slave of SPI. More than 2 devices can be connected by using microcontroller equipped with SPI port. By using a microcontroller not equipped with SPI port, SI and SO can be bus connected to use.



■ STATUS REGISTER

Bit No.	Bit Name	Function
7	WPEN	Status Register Write Protect This is a bit composed of nonvolatile memories (FRAM). WPEN protects writing to a status register (refer to "■ WRITING PROTECT") relating with WP input. Writing with the WRSR command and reading with the RDSR command are possible.
6 to 4	_	Not Used Bits These are bits composed of nonvolatile memories, writing with the WRSR command is possible, and "000" is written before shipment. These bits are not used but they are read with the RDSR command.
3	BP1	Block Protect This is a bit composed of nonvolatile memory. This defines block size for
2	BP0	writing protect with the WRITE command (refer to "■ BLOCK PRO-TECT"). Writing with the WRSR command and reading with the RDSR command are possible.
1	WEL	Write Enable Latch This indicates an FRAM Array and status register are writable. The WREN command is for setting, and the WRDI command is for resetting. With the RDSR command, reading is possible but writing is not possible with the WRSR command. WEL is reset after the following operations. The time when power is up. The time when the WRDI command is input. The time when the WRSR command is input. The time when the WRITE command is input.
0	0	This is a bit fixed to "0".

■ OP-CODE

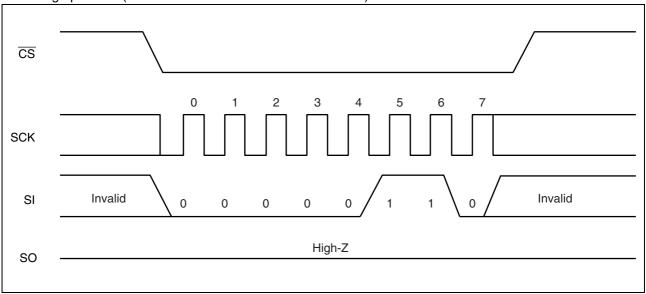
MB85RS128A accepts 6 kinds of command specified in op-code. Op-code is a code composed of 8 bits shown in the table below. Do not input invalid codes other than those codes. If $\overline{\text{CS}}$ is risen while inputting op-code, the command are not performed.

Name	Description	Op-code
WREN	Set Write Enable Latch	0000 0110в
WRDI	Reset Write Enable Latch	0000 0100в
RDSR	Read Status Register	0000 0101в
WRSR	Write Status Register	0000 0001в
READ	Read Memory Code	0000 0011в
WRITE	Write Memory Code	0000 0010в

■ COMMAND

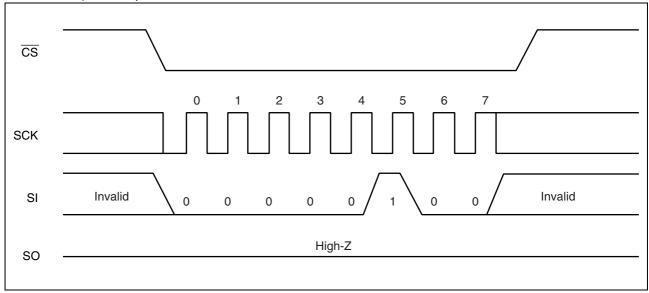
• WREN

The WREN command sets WEL (Write Enable Latch) . WEL has to be set with the WREN command before writing operation (WRSR command and WRITE command) .



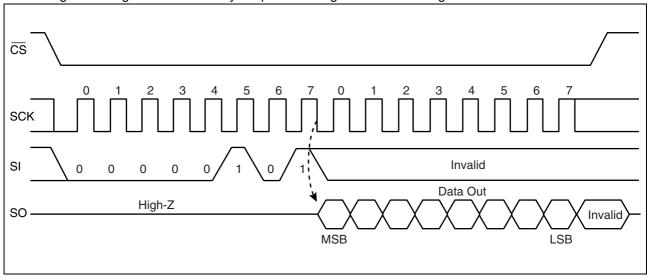
• WRDI

The WRDI command resets WEL (Write Enable Latch) . Writing operation (WRITE command and WRSR command) are not performed when WEL is reset.



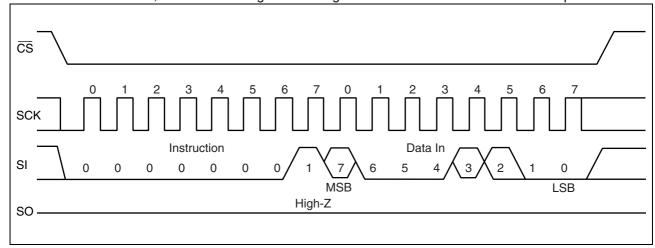
• RDSR

The RDSR command reads status register data. After op-code of RDSR is input to SI, 8-cycle clock is input to SCK. The SI value is invalid for this time. SO is output synchronously to a falling edge of SCK. Continuously reading status register is enabled by keep on sending SCK before rising CS with the RDSR command.



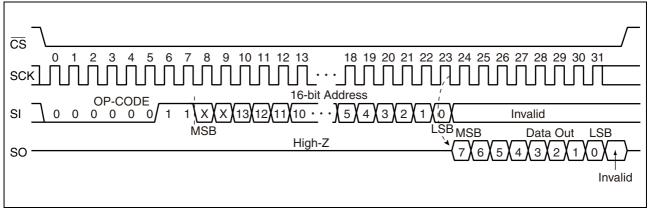
• WRSR

The WRSR command writes data to the nonvolatile memory bit of status register. After performing WRSR op-code to a SI pin, 8 bits writing data is input. WEL (Write Enable Latch) is not able to be written with WRSR command. A SI value correspondent to bit 1 is ignored. Bit 0 of the status register is fixed to "0" and cannot be written. The SI value corresponding to bit 0 is ignored. The $\overline{\text{WP}}$ signal level shall be fixed before performing the WRSR command, and do not change the $\overline{\text{WP}}$ signal level until the end of command sequence.



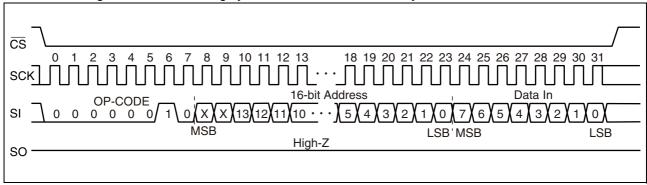
• READ

The READ command reads FRAM memory cell array data. Arbitrary 16 bits address and op-code of READ are input to SI. The 2-bit upper address bit is invalid. Then, 8-cycle clock is input to SCK. SO is output synchronously to the falling edge of SCK. While reading, the SI value is invalid. When \overline{CS} is risen, the READ command is completed, but keeps on reading with automatic address increment which is enabled by continuously sending clock for 8 cycles each to SCK before \overline{CS} is risen. When it reaches the most significant address, it rolls over to come back to the starting address, and reading cycle keeps on infinitely.



• WRITE

The WRITE command writes data to FRAM memory cell array. WRITE op-code, arbitrary 16 bits of address and 8 bits of writing data are input to SI. The most significant address bit is invalid. When 8 bits of writing data is input, data is written to FRAM memory cell array. Risen \overline{CS} will terminate the WRITE command, but if you continue sending the writing data for 8 bits each before \overline{CS} is risen, it is possible to continue writing with automatic address increment. When it reaches the most significant address, it rolls over, comes back to the starting address, and writing cycle can be continued infinitely.



■ BLOCK PROTECT

Writing protect block is configured by the WRITE command with BP1, BP0 value of the status register.

BP1	BP0	Protected Block
0	0	None
0	1	3000н to 3FFFн (upper 1/4)
1	0	2000н to 3FFFн (upper 1/2)
1	1	0000н to 3FFFн (all)

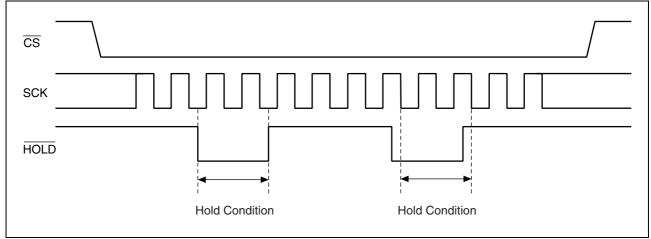
■ WRITING PROTECT

Writing operation of the WRITE command and the WRSR command are protected with the value of WEL, WPEN, WP as shown in the table.

WEL	WPEN	WP	Protected Blocks	Unprotected Blocks	Status Register
0	Х	Х	Protected	Protected	Protected
1	0	Х	Protected	Unprotected	Unprotected
1	1	0	Protected	Unprotected	Protected
1	1	1	Protected	Unprotected	Unprotected

■ HOLD OPERATION

Hold status is retained without aborting a command if HOLD is the "L" level while \overline{CS} is the "L" level. The timing for starting and ending hold status depends on the SCK to be the "H" level or the "L" level when a HOLD pin input is transited to the hold condition as shown in the diagram below. Arbitrary command operation is interrupted in hold status, SCK and SI inputs become don't care. And, SO becomes High-Z while reading command (RDSR, READ) . If \overline{CS} is risen with hold status, a command is aborted and device is reset.



■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rat	Unit	
Parameter	Symbol	Min	Max	Offic
Power supply voltage*	V _{DD}	- 0.5	+ 4.0	V
Input voltage*	VIN	- 0.5	V _{DD} + 0.5	V
Output voltage*	V out	- 0.5	V _{DD} + 0.5	V
Operation ambient temperature	TA	- 40	+ 85	°C
Storage temperature	Tstg	- 40	+ 125	°C

^{*:} These parameters are based on the condition that Vss is 0 V.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol		Unit		
Parameter	Symbol	Min	Тур	Max	Oilit
Power supply voltage*	V _{DD}	3.0	3.3	3.6	V
Input high voltage*	V _{IH}	$V_{DD} \times 0.8$	_	V _{DD} + 0.5	V
Input low voltage*	VıL	- 0.5	_	+ 0.6	V
Operation ambient temperature	TA	- 40	_	+ 85	°C

^{*:} These parameters are based on the condition that Vss is 0 V.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure. No warranty is made with respect to uses, operating conditions, or combinations not represented

on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

■ ELECTRICAL CHARACTERISTICS

1. DC Characteristics

(within recommended operating conditions)

Parameter	Symbol	Condition		Unit		
Parameter	Syllibol	Condition	Min	Тур	Max	Offic
Input leakage current	Iu	$V_{IN} = 0 V to V_{DD}$	_	_	10	μΑ
Output leakage current	ILO	$V_{\text{OUT}} = 0 \text{ V to } V_{\text{DD}}$	_	_	10	μΑ
Operating power supply current	Поо	SCK = 25 MHz	_	5	10	mA
Standby current	Isв	All inputs V_{SS} or $SCK = SI = \overline{CS} = V_{DD}$	_	9	50	μА
Output high voltage	Vон	Iон = −2 mA	$V_{\text{DD}} \times 0.8$	_	_	V
Output low voltage	Vol	IoL = 2 mA	_	_	0.4	V

2. AC Characteristics

Parameter	Symbol	Va	alue	Unit
Parameter	Symbol	Min	Max	Unit
SCK clock frequency	fск	0	25	MHz
Clock high time	tсн	20	_	ns
Clock low time	tcL	20		ns
Chip select set up time	tcsu	10	_	ns
Chip select hold time	tcsн	10	_	ns
Output disable time	top	_	20	ns
Output data valid time	todv	_	18	ns
Output hold time	tон	0	_	ns
Deselect time	to	60	_	ns
Data in rise time	t _R	_	50	ns
Data fall time	te	_	50	ns
Data set up time	tsu	5	_	ns
Data hold time	tн	5	_	ns
HOLD set up time	tнs	10	_	ns
HOLD hold time	tнн	10	_	ns
HOLD output floating time	tнz	_	20	ns
HOLD output active time	tız	_	20	ns

AC Test Condition

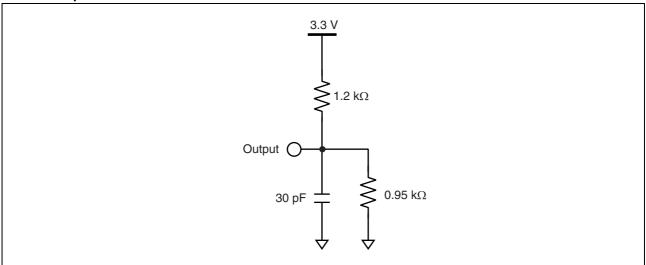
Power supply voltage : 3.0 V to 3.6 V

Operation ambient temperature : $-40~^{\circ}\text{C}$ to $+85~^{\circ}\text{C}$

Input voltage magnitude: 0.3 V to 2.7 V

Input rising time : 5 ns
Input falling time : 5 ns
Input judge level : VDD/2
Output judge level : VDD/2

AC Load Equivalent Circuit

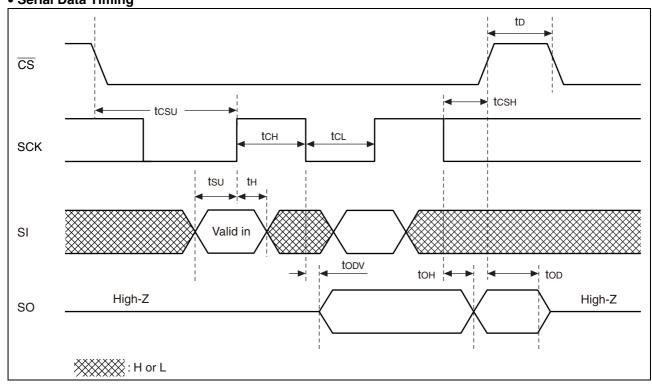


3. Pin Capacitance

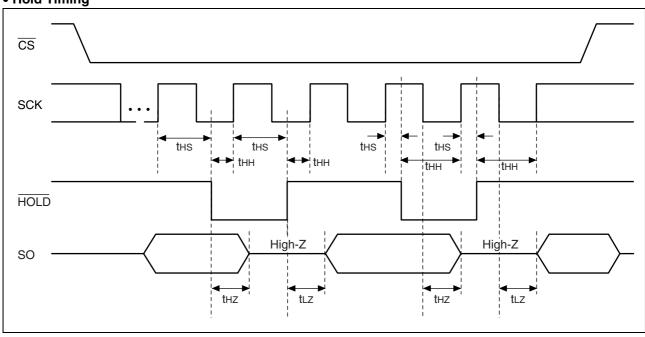
Parameter	Symbol	Conditions	Va	Unit	
Faranietei	Syllibol	Conditions	Min	Max	Oilit
Output capacitance	Со	$V_{DD} = V_{IN} = V_{OUT} = 0 V,$	_	10	pF
Input capacitance	Cı	$f = 1 \text{ MHz}, T_A = +25 ^{\circ}\text{C}$		10	pF

■ TIMING DIAGRAM

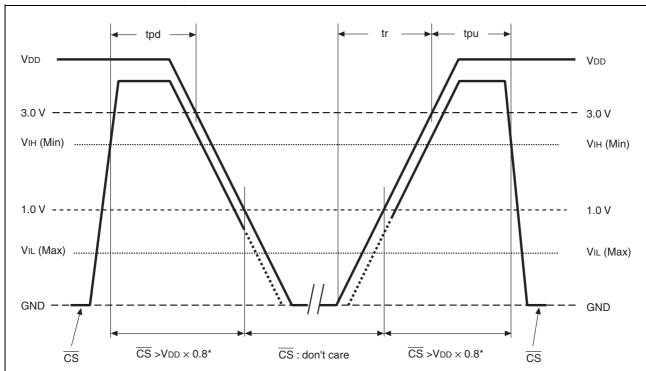
• Serial Data Timing



• Hold Timing



■ POWER ON/OFF SEQUENCE



* : \overline{CS} (Max) < $V_{DD} + 0.5 V$

Notes: • Because turning the power-on from an intermediate level may cause malfunctions, when the power is turned on, V_{DD} is required to be started from 0 V.

• If the device does not operate within the specified conditions of read cycle, write cycle, or power on/ off sequence, data in the memory can not be guaranteed.

Parameter	Symbol	Va	Unit	
Farameter	Syllibol	Min	Max	Ollit
CS level hold time at power OFF	tpd	200	_	ns
CS level hold time at power ON	tpu	85	_	ns
Power supply rising time	tr	0.05	200	ms

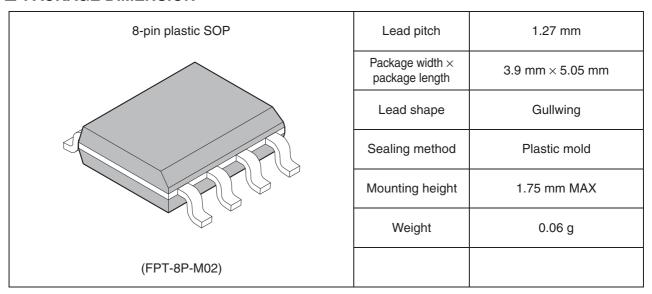
■ NOTES ON USE

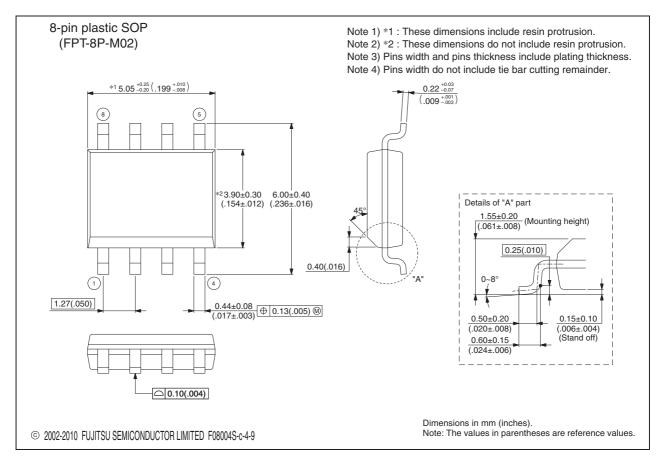
Data written before performing IR reflow is not guaranteed after IR reflow.

■ ORDERING INFORMATION

Part number	Package	Shipping form	Minimum shipping quantity
MB85RS128APNF-G-JNE1	8-pin plastic SOP (FPT-8P-M02)	Tube	1
MB85RS128APNF-G-JNERE1	8-pin plastic SOP (FPT-8P-M02)	Embossed Carrier tape	1500

■ PACKAGE DIMENSION





Please check the latest package dimension at the following URL. http://edevice.fujitsu.com/package/en-search/

■ MAJOR CHANGES IN THIS EDITION

A change on a page is indicated by a vertical line drawn on the left side of that page.

Page	Section	Change Results
1	■ FEATURES	Changed the order of items.
	Package	Added "RoHS Compliant".
6	■ STATUS REGISTER	Changed the Function of WPEN. WPEN is related to WP input to protect writing to a status register (refer to "■ WRITING PROTECT") → WPEN protects writing to a status register (refer to "■ WRITING PROTECT") relating with WP input.
		Changed the explanation of WEL. FRAM Memory → FRAM Array
8	■ COMMAND • WRSR	Added "The \overline{WP} signal level shall be fixed before performing the WRSR command, and do not change the \overline{WP} signal level until the end of command sequence".
12	■ ELECTRICAL CHARACTERISTICS 1. DC Capacitance	Changed the typical value of stanby-current. 3 $\mu A \rightarrow$ 9 μA
14	3. Pin Capacitance	Added the row of "Conditions" to the table. Conditions; $V_{DD} = V_{IN} = V_{OUT} = 0 \ V, \ f = 1 \ MHz, \ T_A = \ + \ 25 \ ^{\circ}C$
15	■ TIMING DIAGRAM • Serial Data Timing	Changed the timing diagram.
17	■ORDERING INFORMATION	Changed the part numbers from TBD. MB85RS128APNF-G-JNE1 MB85RS128APNF-G-JNERE1
		Added row of the minimum shipping quantity. Minimum shipping quantity; Tube : 1 Embossed Carrier tape: 1500

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